



Product Change Notification / ALAN-08K00J271

Date:

04-Aug-2022

Product Category:

32-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4767 Final Notice: Qualification of ANAP as an additional assembly site for selected Atmel AT91SAM7S1xx and AT91SAM7S2xx device families in 64L LQFP (10x10x1.4mm) package.

Affected CPNs:

[ALAN-08K00J271_Affected_CPN_08042022.pdf](#)
[ALAN-08K00J271_Affected_CPN_08042022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ANAP as an additional assembly site for selected Atmel AT91SAM7S1xx and AT91SAM7S2xx device families in 64L LQFP (10x10x1.4mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change
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Assembly location		ASE Inc. (ASEK)	ASE Inc. (ASEK)	Amkor Technology Philippine (P1/P2), INC. (ANAP)
Bond wire material		CuPdAu	CuPdAu	CuPdAu
Die attach material		CRM-1076WA	CRM-1076WA	3230
Mold compound material		G631HQ	G631HQ	G631HQ
Lead-frame	Material	C7025	C7025	C194
	Process	Stamped	Stamped	Etched
	Paddle Size	250x250 mils	250x250 mils	295x295 mils
	See pre and post change comparison			

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity by qualifying ANAP as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:September 1, 2022 (date code: 2236)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2022				September 2022				
	32	33	34	35	36	37	38	39	40
Qual Report Availability	x								
Final PCN Issue Date	x								
Estimated Implementation Date					x				

Method to Identify Change:Traceability Code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

July 27, 2021: Issued initial notification

August 25, 2021: Re-issued initial notification to update the molding compound material from G700Y to G631HQ for ANAP assembly site in PCN letter and Qual plan. Updated the Pre and Post change comparison file to reflect the lead frame information only for ASEK and ANAP.

August 4, 2022: Issued final notification. Qualification report attached. Provided estimated first ship date to be on September 1, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_ALAN-08KOOJ271_Pre and Post Change_Summary.pdf](#)

[PCN_ALAN-08KOOJ271_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

AT91SAM7S128D-AU

AT91SAM7S256D-AU

AT91SAM7S256D-AU-999

AT91SAM7S128D-AU-999